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SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE POSSESSING MULTIPLE LAYER
OF SEMICONDUCTOR CHIPS

Inventor:	Harike Koksei NEC Corporation 5-33-1 Shiba, Minato-ku, Tokyo
Applicant:	NEC Corporation 5-33-1 Shiba, Minato-ku, Tokyo
Agent:	Susumi Uchihara, patent attorney

Claim

In semiconductor integrated circuit devices, a semiconductor integrated circuit device characterized by a construction in which, on top of a semiconductor integrated circuit chip housed in a container, semiconductor integrated circuit chips smaller than the first one are piled, in a certain order.

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